

ENHANCED DIE-UP BALL GRID ARRAY PACKAGE WITH TWO
SUBSTRATES AND METHOD FOR MAKING THE SAME

ABSTRACT OF THE DISCLOSURE

An electrically and thermally enhanced die-up ball grid array (BGA) package is described. An integrated circuit (IC) package includes a first substrate, a second substrate, and a stiffener. A surface of the first substrate is attached to a first surface of the stiffener. A surface of the second substrate is attached to a second surface of the stiffener. An IC die may be attached to a second surface of the second substrate or to the second surface of the stiffener. Additional electronic devices may be attached to the second surface of the second substrate.

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